Build Up HDI (Standard)

HDI08_2+4+2_1,00_17.5_engl

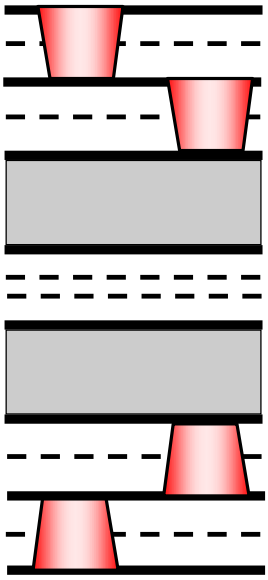
8 - Layers

Core: 0,25 mm Cu 17.5/17.5 µm

WE-Articel No.: | **2 + 4 + 2**

Customer:

WÜRTH ELEKTRONIK

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	60	
	2		Foil	12 µm		30	
					1 x 1080	66	
	3			17.5 µm		16	
			0,250 mm			250	
	4			17.5 µm		16	
					2 x 1080	134	
	5			17.5 µm		16	
			0,250 mm			250	
	6			17.5 µm		16	
					1 x 1080	66	
	7		Foil	12 µm		30	
					1 x 1080	60	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 1034

Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	**1,00**	+/-	0,08	mm			Date: / Engineer:
thickness with electro plated Cu:	1,09	+/-	0,11	mm			
total thickness with soldermask	1,15	+/-	0,13	mm			
customer requirement		+/-		mm	point:		

prepared: on	by	checked: on	by	approved: on	by	revision	
25.04.2006	**S. Keller**	04.05.2006	M.Kress	25.04.2006	R. Schönholz	00	page: 12+